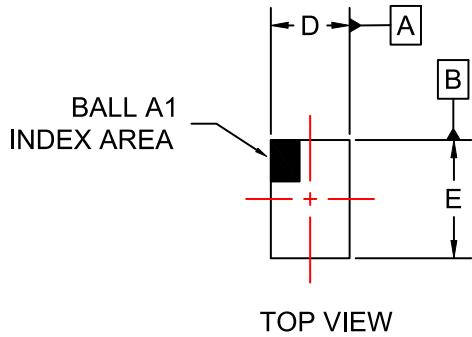


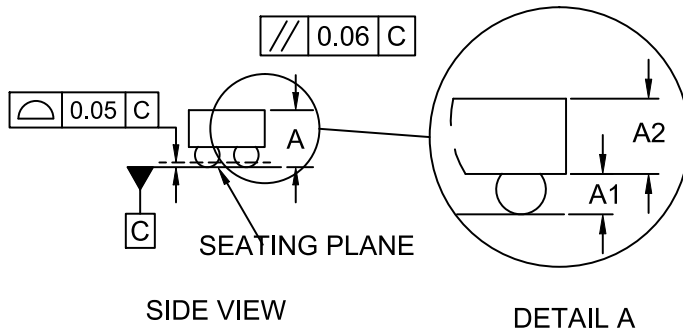
**WLCSP6 1.16x0.86x0.586**  
CASE 567RQ  
ISSUE A

DATE 12 JAN 2018

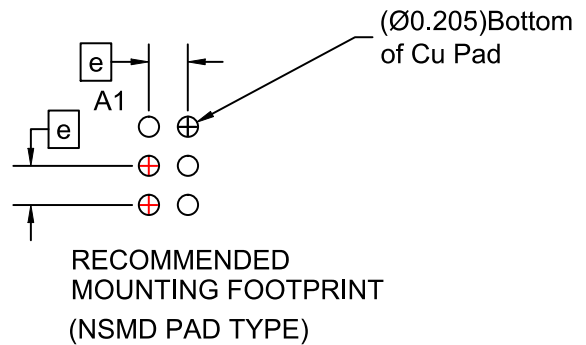
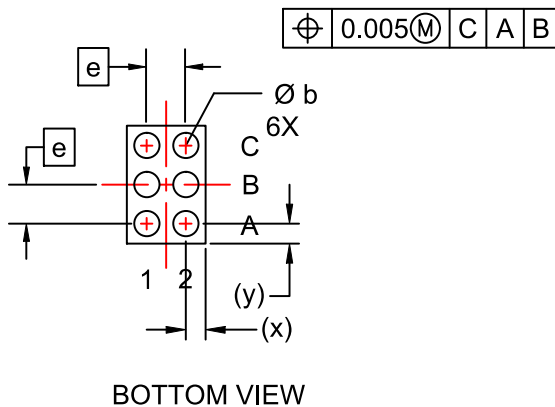


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MIN.	NOM.	MAX.
A	0.547	0.586	0.625
A1	0.187	0.208	0.229
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	0.830	0.860	0.890
E	1.130	1.160	1.190
e	0.40 BSC		
x	0.215	0.230	0.245
y	0.165	0.180	0.195



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<b>DESCRIPTION:</b>	<b>WLCSP6 1.16x0.86x0.586</b>	<b>PAGE 1 OF 1</b>

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